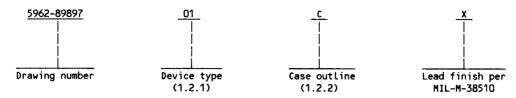

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1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	LT1058A	Quad, precision, high speed, JFET operational amplifier
02	LT1058	Quad, precision, high speed, JFET operational amplifier

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
С	GDIP1-T14 or CDIP2-T14	14	Dual-in-line

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

1/ For case C, for T_A above +75°C, derate linearly at 6.7 mW/°C.

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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and bulletin</u>. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

STANDARDS

MILITARY

MIL-STD-883

- Test Methods and Procedures for Microelectronics.

MIL-STD-1835

- Microcircuit Case Outlines.

BULLETIN

MILITARY

MTI -BUL-103

List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- `3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

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		Conditions 1/	 Group A	Device	lim	its <u>2</u> /	Unit
Test	Symbol	Conditions 1/ -55°C ≤ T _A ≤ +125°C V _S = ±15 V, V _{CM} = 0 V unless otherwise specific	subgrou			1	
<u> </u>		unless otherwise specific			Min	Max	
Input offset voltage	Vos		4	01	-600	600	μν
			2,3		-1600	1600	
		1	4	02	-1000	1000	
	 		2,3		<u>-2500</u> 	2500	
Average temperature coefficient of input offset voltage	V _{TOS}	T _A = +125°C, -55°C <u>3</u> /	2,3	01	-10 -15	+10 +15	μ ν /°C
Input offset	Ios	 	1	01	-40	40	pA
current	-os	Fully warmed up, T _A = +25°C, +125°C	2		-2	2	nA
			1	02	-50	50	pA
			2		-3	3	nA
	1.	Fully yeared up	1	01	-50	50	p A
Input bias current	I _B	Fully warmed up, T _A = +25°C, +125°C	2	_ "	-4.5	4.5	nA
	-		1	02	-75	1 75	pA
						6	
Supply current	Is	 V_ = 0 V_	2	01	-6	2.5	nA mA
per amplifier	-s	V _O = 0 V, T _A = +25°C, +125°C	2			1.9	
	į		1	02		2.8	 -
	ļ		2			2.2	
Common mode		<u>3</u> /	1 1	ALL	-10.5	+10.5	v
input volt age	V _{CM}	2/	2,3	_ ~~	-10.4	+10.4	
range Common mode rejection ratio	CMRR	V _{CM} = ±10.5 V	4	01	84	110.4	dB
	İ	V _{CM} = ±10.4 V	5,6		84]
		V _{CM} = ±10.5 V	4	02	80		
		V _{CM} = ±10.4 V	5,6		80		
See footnotes at end	of table.						
STANDARDIZED MILITARY DRAWING			SIZE			596	2-89897
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Test	Symbol	Conditions -55°C ≤ T _A ≤ +125'	Group A	Device type	Limi	ts <u>2</u> /	Unit		
		$-55^{\circ}C \le T_{A} \le +125^{\circ}$ $V_{S} = \pm 15 \text{ V, } V_{CM} = 0$ unless otherwise sp	0 V ecified		<u> </u>	Min	Max	<u> </u>	
ower supply	PSRR	v _S = ±10 V to ±18 V		1	01	88		dB	
rejection ratio				<u> </u>	02	86			
		V _S = ±10 V to ±17 V		2,3	01	86			
				 	02	83		<u> </u>	
ain bandwidth	GBW	f _O = 1 MHz, <u>3</u> / T _A = +25°C	f _O = 1 MHz, <u>3</u> /		01	3.5		MHz	
product		T _A = +25°C		<u> </u>	02	3			
output voltage swing	+V _{OUT}	R _L = 2 kΩ	R _L = 2 kΩ			+12		. v	
	-V _{OUT}					<u> </u>	-12		
arge signal	A _{VOL}	 V _O = ±10 V	$R_L = 2 k\Omega$	4	01	150	<u> </u>	 V/mV	
voltage gain			-			100			
				5,6	01	40	<u> </u> 	_	
	1				02	30	! 	-	
			$ R_1 = 1 k\Omega$	2 4	01	120	<u> </u>	-	
		1		<u>L</u>	02	80		<u> </u>	
Input noise	 e _n	 f ₀ = 1 kHz, <u>3</u> /	= 1 kHz, <u>3</u> /		01	<u> </u>	22	 nV/√Hz	
voltage density	"	TA = +25°C			02		24	_	
Input noise	In	f _O = 10 kHz, 1 kHz, T _A = +25°C <u>4</u> /	<u>3</u> /	4	01		4_	fA/√Hz	
current density	_ "	TA = +25°C 4/		İ	02		6	<u> </u>	
Slew rate	+SR		,	7	01	10		_ V/μs	
	į	R _L = ∞, c _L = 0 pF, A _{VCL} = +2, V _{OUT} = -10 V to +10) v,		02	8		-	
	}	measured at -7 V to rising edge	5 +7 V,	8 <u>3</u> /	01	7			
	1				02	5			
	-SR	R _L = ∞, C _L = 0 pF,	,	7	01	10			
		A _{VCL} = +2, V _{OUT} = -10 V to +10 measured at -7 V to) V,		02	8			
		measured at -7 V to falling edge	o +7 V,	8 <u>3</u> /	01	7	<u> </u>	_	
				 02	5				
	1								
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TABLE I. <u>Electrical performance characteristics</u> - Continued.

- $1/R_1$ is actual resistance from output to ground, and f_0 is test frequency. $1/R_2$ The algebraic convention, whereby, the most negative value is a minimum and the most positive is a maximum, is used in this table. Negative current shall be defined as conventional current flow out of a device terminal.
- 3/ If not tested, shall be guaranteed to the limits specified in table I herein.

 4/ Current noise is calculated from the formula $I_N = (2 \times q \times I_B)^2$ where $q = 1.6 \times 10^{19}$ coulomb. The noise of source resistors up to 1 G Ω swamps the contribution of current noise.
- 3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition C using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition C using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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Device types	01 and 02
Case outline	С
Terminal number	Terminal symbol
1	OUTPUT A
2] -INPUT A
3	+INPUT A
4	+V _e
5	+INPUT B
6	-INPUT B
7	OUTPUT B
8	OUTPUT C
9	-INPUT C
10	+INPUT C
11	-V _S
12	+INPUT D
13	-INPUT D
14	OUTPUT D

FIGURE 1. Terminal connections.

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TABLE II. <u>Electrical test requirements</u>.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 4, 5, 6, 7
Group A test requirements (method 5005)	1, 2, 3, 4, 5, 6, 7, 8
Group C and D end-point electrical parameters (method 5005)	1

^{*} PDA applies to subgroup 1.

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6021.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone (513) 296-5377.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS.

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